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ISSUE CLASSIFICATION	
Class	Subclass

~~PATENT NUMBER~~

50-2
TL-863

O.I.P.E. <i>RT</i> SCANNED <i>12/15/11</i> Q.A. <i>11/11</i>	PATENT DATE
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APPLICATION NO. 09/634209	CONT/PRIOR	CLASS 257 43	SUBCLASS 118	ART UNIT 2814	EXAMINER H. J. Pinner
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Stephen Park
Christian Zistel

Depth of focus (DOF) for trench-first-via-last (TFVL) damascene processing with hard mask and low viscosity photoresist

PTO-2040
12/89[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner)		NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____	_____ (Primary Examiner)		ISSUE FEE	
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<input type="checkbox"/> The terminal ____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner)		ISSUE BATCH NUMBER	
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